US00D614152S

(12) United States Design Patent

Lee et al.

(10) **Patent No.:** **US D614,152 S**

(45) **Date of Patent:** ** ***Apr. 20, 2010**

(54) **SUBSTRATE TRANSFER DEVICE FOR SEMICONDUCTOR DEPOSITION APPARATUS**

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(**) Term: **14 Years**

(21) Appl. No.: **29/331,021**

(22) Filed: **Jan. 16, 2009**

(30) **Foreign Application Priority Data**

Jul. 21, 2008 (KR) 30-2008-0031456

(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** D13/182; 134/110; 361/234; 396/611; 414/331.15, 414/411, 416.03; 700/213

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a substrate transfer device for semiconductor deposition apparatus, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a substrate transfer device that may be positioned in a semiconductor deposition apparatus, showing our new design;

FIG. **2** is a front elevation view thereof;

FIG. **3** is a rear elevation view thereof;

FIG. **4** is a left side elevation view thereof;

FIG. **5** is a right side elevation view thereof;

FIG. **6** is a top plan view thereof; and,

FIG. **7** is a bottom plan view thereof.

The ornamental design which is claimed is shown in solid lines in the drawings.

1 Claim, 5 Drawing Sheets

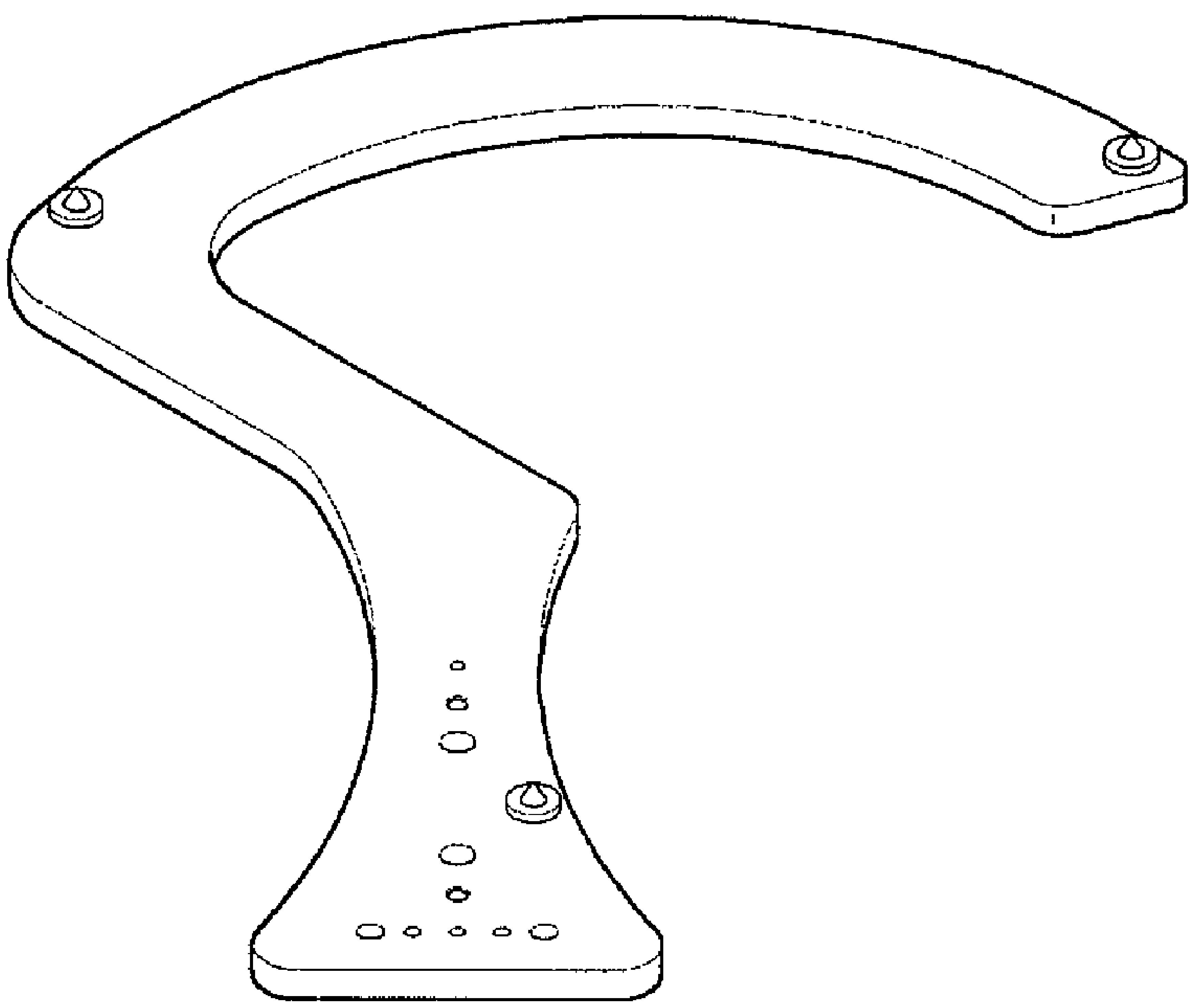

FIG. 1

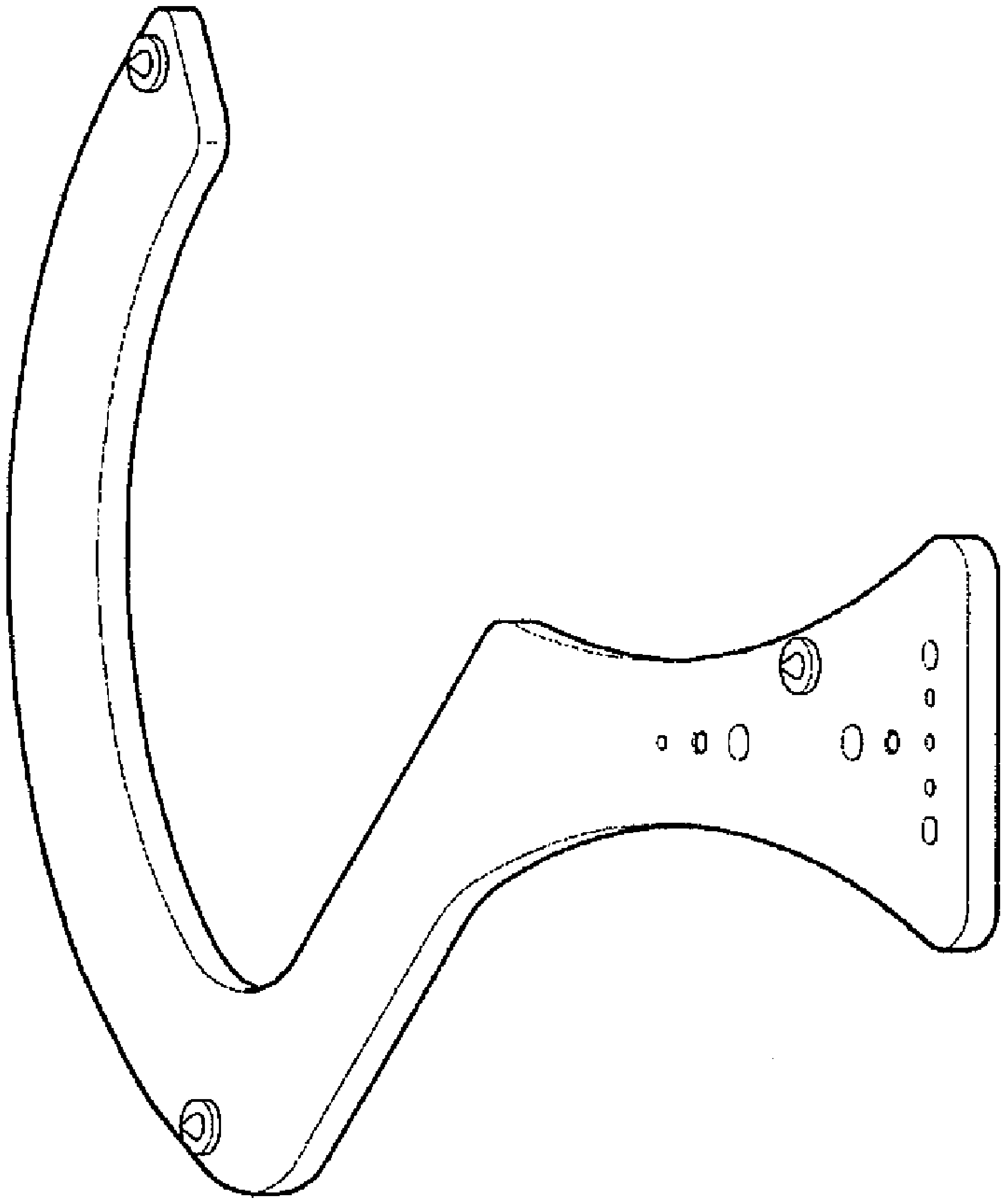

FIG. 2

FIG. 3

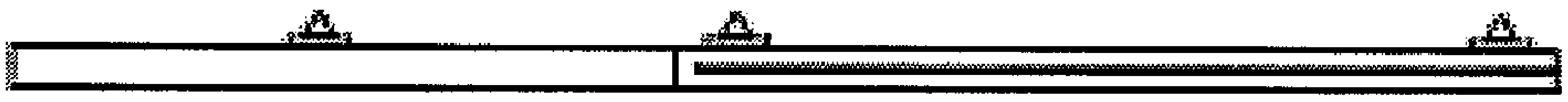

FIG. 4

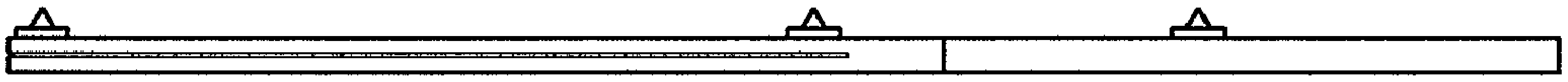

FIG. 5

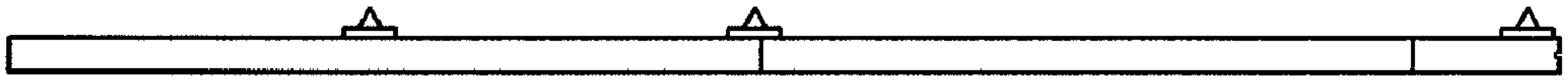

FIG. 6

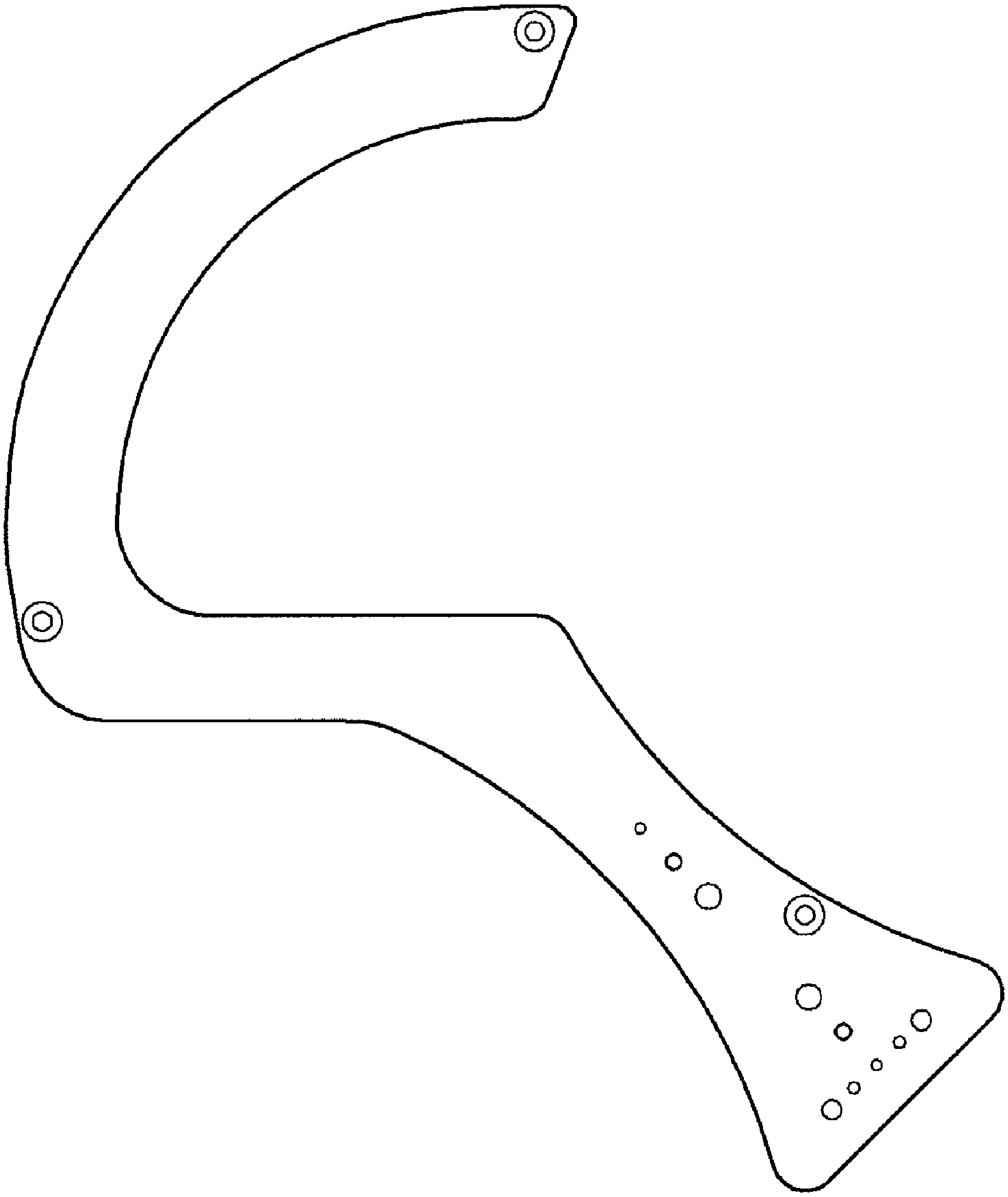

FIG. 7